

Patent Application
Docket No.27889-37

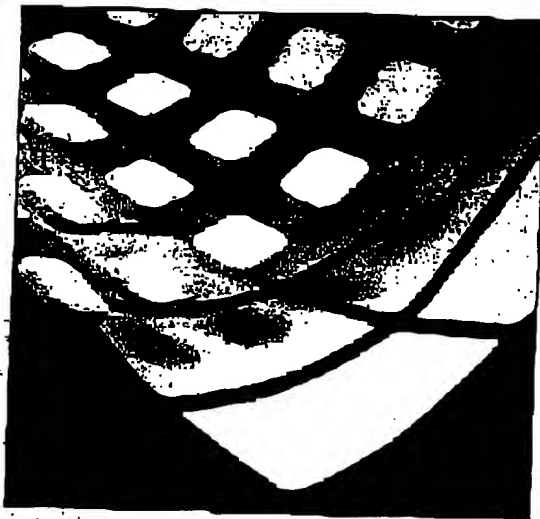
Exhibit A

Advertisements for "thermal interface materials"

1. W.L. Gore and Associates, Inc.'s POLARCHIP™
2. Thermalloy, Inc.'s Thermalcote II
3. Stockwell Rubber Company's Thermal Management Components

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POLARCHIP Materials are An Ideal "Gap-Filler" for Large or Variable Gaps

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Reader Interest Rating

Please circle the appropriate Reader Inquiry Number in your response form to indicate your level of interest in this article.

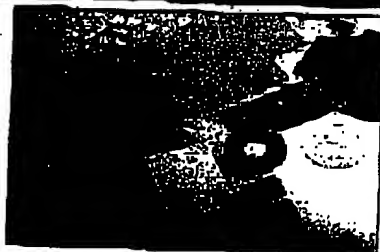
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References

1. M. Linzell, P. Smith, O. Carey, P. Sanderson, 1998, "The Role of Physical Implementation in Virtual Prototyping of Electronic Systems", IEEE Trans. CPMT, Part A, Vol. 21, No. 4, pp. 611-626.
2. M. Pecht, 1998, "Why the traditional reliability prediction models do not work - is there an alternative?", ElectronicsCooling, Vol. 2, No. 1, pp. 10-12.
3. G. Oak, 1999, "Use of Thermal Analysis Information in Avionics Equipment Development", ElectronicsCooling, Vol. 5, No. 2, pp. 28-34.
4. M. Osterman, 2001, "We all have a headache with Arrhenius", ElectronicsCooling, Vol. 7, No. 1, pp. 53-64.
5. R. Lall, M. Pecht, G. Hekim, 1997, "Influence of temperature on Microelectronics and System reliability", CRC Press, New York.
6. <http://stanford.edu/org/catef/reliability.html>
7. D. Munshy, J. Gordin, N. Pandya, D. Das, C. Winkler, M. Pecht, 2000, "An Avionics Guide to Upgrading of Electronic Parts", IEEE Trans. CPMT, Part A, Vol. 23, No. 3, pp. 585-599.
8. M. Jackson, P. Lall, D. Oak, 1997, "Thermal Densifying - A Factor of Safety or Ignorance", IEEE Trans. CPMT, Part A, Vol. 20, No. 1, pp. 88-95.
9. C. Lasance, 2001, "The Comparable Accuracy of Experimental and Numerical Thermal Analyses of Electronic Systems", Proc. 17th SEMI-THERM, pp. 190-198.
10. C. Lasance, 2001, "The European Project PROFIT: Prediction of Temperature Gradients Influencing the Quality of Electronic Products", Proc. 17th SEMI-THERM, pp. 120-126.

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